

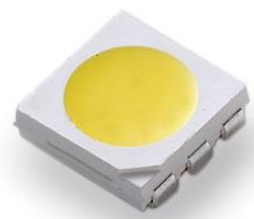


TECHNOLOGY DATA SHEET & SPECIFICATIONS

MODEL: 5050SUW3C

Features

- InGaN White*3 Dice LED
- Size : 5.0mm×5.0mm×1.5mm
- High luminous intensity, high reliability and long life
- With ROHS Compliant



Descriptions

- The 5050 SMD LED is much smaller than lead frame type components thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained
- Besides, lightweight makes them ideal for miniature applications.etc

Usage Notes:

- Surge will damage the LED
- When using LED, it must use a protective resistor in series with DC current about 50mA

Applications

- Amusement equipment ·
- Information boards ·
- Flashlight for digital camera of cellular phone ·
- Lighting for small size device.

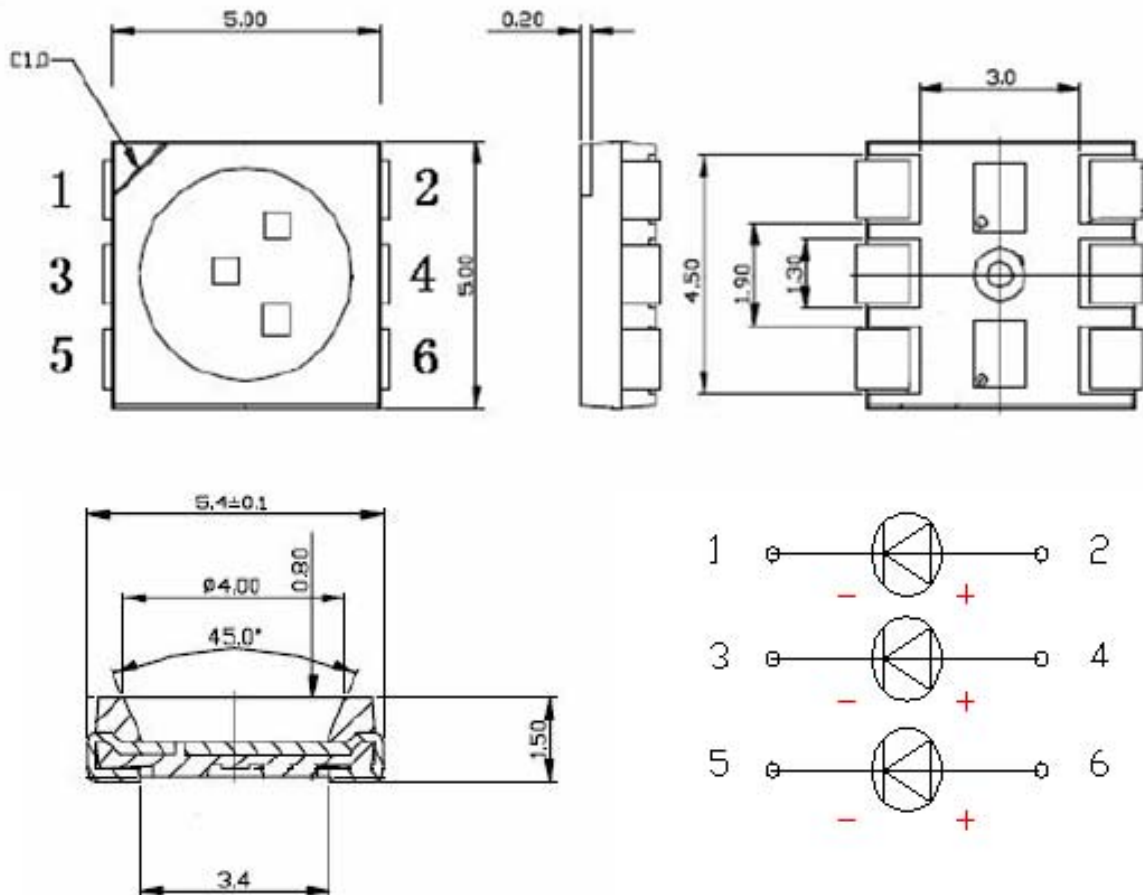
Device Selection Guide

LED Part No.	Chip		Lens Color
	Material	Emitted Color	
5050SUW3C	InGaN	Warm White	Water clear

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Package Dimensions



Notes:

- Other dimensions are in millimeters, tolerance is 0.25mm except being specified.
- Protruded resin under flange is 1.5mm Max LED.
- Bare copper alloy is exposed at tie-bar portion after cutting.



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Electro-Optical Characteristics (T_a=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	---	15	---	LM	IF=50mA(Note1)
Viewing Angle	2θ _{1/2}	---	120	---	Deg	(Note 2)
Color Temperature	CT	3000	---	4500	K	IF=50mA
Spectral Line Half-Width	Δλ	---	30	25	nm	IF=50mA
Forward Voltage	V _F	3.0	---	3.4	V	IF=50mA
Reverse Current	I _R	---	---	50	μA	VR=5V

Note:

1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
2. θ_{1/2} is the off-axis angle at which the luminous intensity is half the axial luminous intensity.



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APPLICATION NOTES:

1)Soldering:

① Manual soldering by soldering iron:

The use of a soldering iron of less than 25W is recommended and the temperature of the iron must be kept at no higher than 300℃.

② Reflow soldering:

a. The temperature profile as shown in Fig.3 is recommended for soldering SMD LED by the reflow furnace.

b. Care must be taken that the products be handled after their temperature has dropped down to the normal room temperature after soldering.

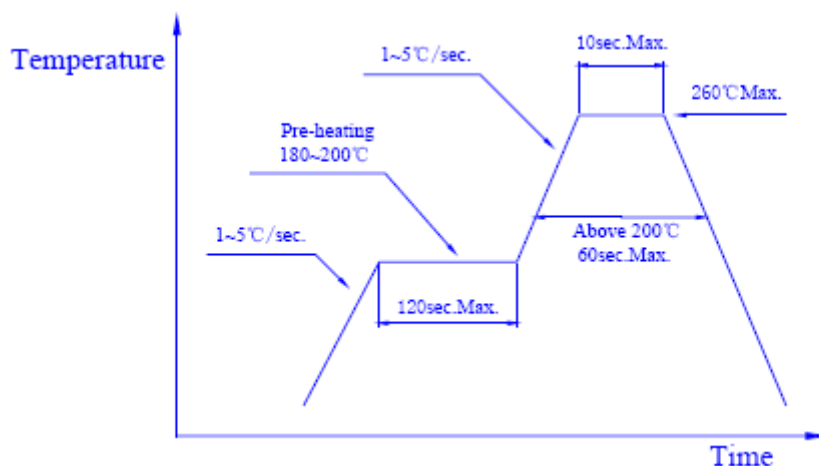


Fig.3

2)Post solder cleaning:

When cleaning after soldering is needed, the following conditions must be adhered to.

① Cleaning solvents: Freon TF or equivalent or alcohol.

② Temperature: 50℃ Max.for 30 seconds or 30℃Max.for 3 minutes



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③ Ultrasonic: 300W Max.

3) OTHERS:

a. Care must be taken not to cause stress to the epoxy resin portion of SMD LED while it is exposed to the high temperature.

b. Care must be taken not to rub the epoxy resin portion of SMD LED with a hard or sharp edged article such as the sand blast and the metal hook as the epoxy resin is rather soft and liable to be damaged.